WAFER PROCESSING METHOD

ABSTRACT

A wafer processing method for dividing a wafer into individual devices along division lines formed on the front side of the wafer is disclosed. The wafer processing method includes a protective tape attaching step of attaching a protective tape having an adhesive layer to the front side of a functional layer of the wafer in the condition where the adhesive layer of the protective tape is in contact with the front side of the functional layer, and a wafer dividing step of holding the wafer with the protective tape on a holding surface of a chuck table in the condition where the protective tape is in contact with the holding surface and next applying a laser beam having an absorption wavelength to the substrate and the functional layer of the wafer from the back side of the substrate along each division line to form a laser processed groove having a depth reaching the protective tape along each division line, thereby dividing the wafer into individual device chips corresponding to the individual devices. (Figure 4C)